

FIG. 1 (PRIOR ART)

FIG. 2 is a cross-sectional view of a device 200. The device 200 includes a substrate 230. A layer 210 is disposed on the substrate 230. The layer 210 includes a first region 212 and a second region 214. A first conductive layer 216 is disposed on the first region 212. A second conductive layer 218 is disposed on the second region 214. A first contact 214 is disposed on the first conductive layer 216. A second contact 215 is disposed on the second conductive layer 218. A first conductive layer 216 is disposed on the first region 212. A second conductive layer 218 is disposed on the second region 214. A first contact 214 is disposed on the first conductive layer 216. A second contact 215 is disposed on the second conductive layer 218. A first conductive layer 216 is disposed on the first region 212. A second conductive layer 218 is disposed on the second region 214. A first contact 214 is disposed on the first conductive layer 216. A second contact 215 is disposed on the second conductive layer 218.

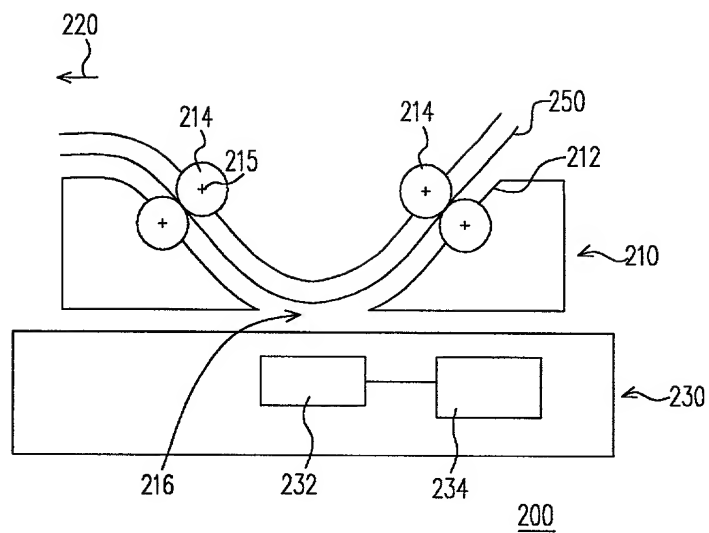


FIG. 2

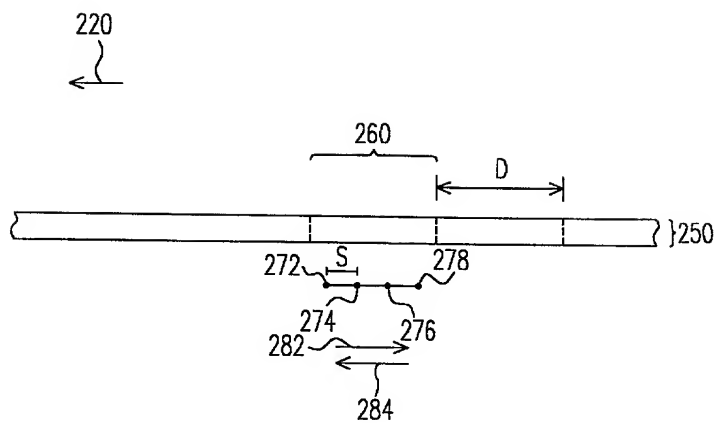


FIG. 3